ON Semiconductor

Update Notification

Document # : FPCN20579XA1
Issue Date: 18 August 2016

Title of Change:	Update Notice of FPCN20579XA – SD05T1G, SD05T3G and SD12T1G products removal as affected devices for dual sourced project.
Proposed first ship date:	7 October 2016
Contact information:	Contact your local ON Semiconductor Sales Office or <eben.lim@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <eben.lim @onsemi.com>.
Type of notification:	ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change category:	☒ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other _____

Change Sub-Category(s):

☒ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☐ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: _____

Sites Affected:

☐ All site(s) ☐ not applicable ☐ ON Semiconductor site(s) :

☒ External Foundry/Subcon site(s)

ADVANCED SEMICONDUCTOR MANUFACTURING CORP LTD

HANGZHOU LION MICROELECTRONICS CO LTD

Description and Purpose:

This Update Notification is issued to inform customers that SD05T1G, SD05T3G and SD12T1G are being removed from the affected list of devices and will no longer be affected by the dual sourcing project.

FPCN20579XA was initially released in 28 Jun 2014 to notify customers of the qualification of ASMC (Advanced Semiconductor Manufacturing Corporation Limited in Shanghai, China) and LiON Microelectronics Corporation Limited in Hang Zhou, China, as second source foundry facilities to the current ON Semiconductor ISMF fabrication facility in Seremban, Malaysia for Zener products.

List of Affected Standard Parts:

SD05T1G
SD05T3G
SD12T1G